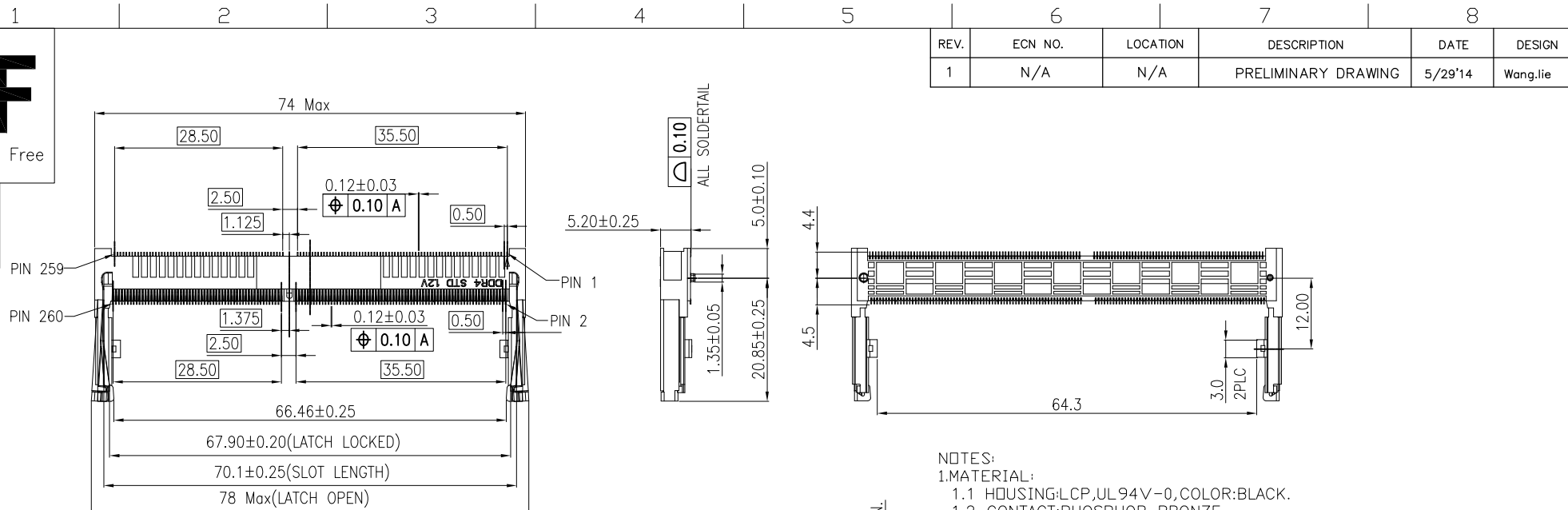


HF

Halogen Free



## NOTES:

## 1. MATERIAL:

- 1.1 HOUSING: LCP, UL94V-0, COLOR: BLACK.
- 1.2 CONTACT: PHOSPHOR BRONZE.
- 1.3 SOLDER PEG AND LATCH: STAINLESS STEEL.

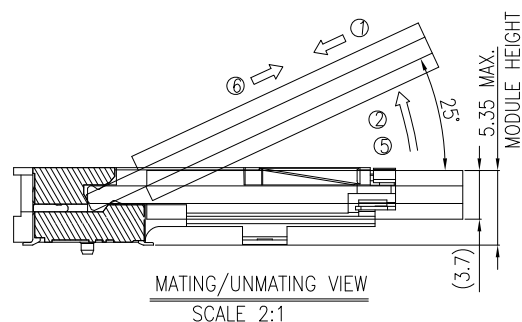
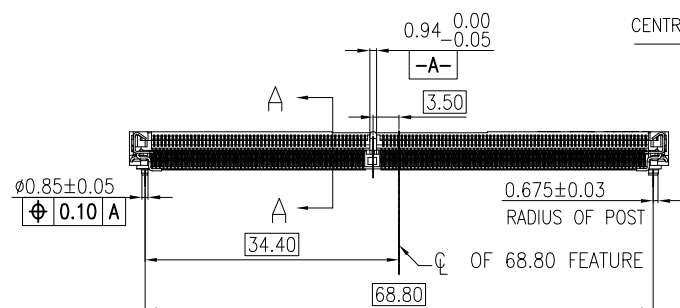
## 2. FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.  
GOLD FLASH PLATING ON SOLDER TAIL.  
GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.
- 2.2 SOLDER PEG:  
50u" MIN NICKEL UNDERPLATED ALL OVER.  
AU 2u" MAX ON SOLDER TAIL.

## 3. PART NUMBER DESCRIPTION:

40-42272-2600XRHF-L

HALOGEN CODE:  
HF: HALOGEN FREE  
R: TAPE & REEL PACKING  
PLATING CODE:  
1: GF 2: Au5u" 3: Au10u"  
4: Au15u" 5: Au30u"  
RESERVED  
PIN NUMBER CODE: 260 PINS



MATING: ① INSERTING(30°) → ② ROTATING → ③ FIXED  
UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

TABLE 2

		DIM	TOL	DIM	TOL
30u" Au	40-42272-26005RHF-L	x.	±0.30	x.	±2°
15u" Au	40-42272-26004RHF-L	.x	±0.25	.x	±1°
10u" Au	40-42272-26003RHF-L	.xx	±0.15		
5u" Au	40-42272-26002RHF-L				
GF	40-42272-26001RHF-L				
PLATING THICKNESS	DEREN P/N				

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.15		

DRAW NO.		DESIGN: Wang.lie		DATE: 5/29'14		TITLE: DDR4 SO DIMM 260P 5.2H STD(FOR LCFC) C-DWG	
REV. 1		CHECK: Bill.lin		DATE: 5/29'14		P/N: SEE TABLE 2	
APPROVAL: Bill.lin		DATE: 5/29'14		SHEET: 1/3		SCALE: 1:1	
				UNIT: mm			

CONSHARE